Samsung Enterprise SSD 2013

Samsung OEM offering			PM843		SM843				SM	843T		SM1625				
Availability		Feb 13			now				Feb 13; 960	GB: March 13		on request				
Interface		SATA 6.0Gbps				SATA 6.0Gbps				6.0Gbps		SAS 6G Dual port				
Target Application		Read intensive, <10% Write content & Streaming Servers, Low cost, Sequential Read Performance			20-30% write Boot Drive / Scratch Drive, Meta data (HPC), Web server, Random read perfromance			extensive read	and Write cache	0% write , Data warehousing mized	g, high edurance	60-70% write Tier 0, Storage servers				
recomme for des		perferct cost sensitive, entry level, Low endurance, High rentention			Mid range endurance, High rentention, low latency			-		ween cost and edu th Storage Firmwa		high Endurance and high performance				
Part numbers		MZ7TD120HAFV- 000DA	MZ7TD240HAFV- 000DA	MZ7TD480HAGM- 000DA	MZ7PD120HAFV- 000DA	MZ7PD240HAFV- 000DA	MZ7PD480HAGM- 000DA	MZ7WD120HAFV- 00003	MZ7WD240HAFV- 00003	MZ7WD480HAGM- 00003	MZ7WD960HAGP- 00003 MZ6ER100HAFV- 00003		MZ6ER200HAG M-00003	MZ6ER400HAGL- 00003	MZ6ER800HAGL- 00003	
Capac	cities	120 GB	240 GB	480 GB	120 GB	240 GB	480 GB	120 GB	240 GB	480 GB	960 GB	100 GB	200 GB	400 GB	800 GB	
relative price ba	all park per GB		100%			113%			13	38%			338%			
Reter virgin SSD / by guar		1	LO years / 3 mont	ths	10 years / 3 months				10 years	/ 3 months		10 years / 3 months				
Warranty (lo			3 years OR TBW	I	5years OR TBW				5years	OR TBW		5years OR TBW				
TBW (Total Bytes 1) 100% 64KB		207 TB	415 TB	830 TB	1 PB	2 PB	4 PB	2 PB	4 PB	8 PB	16 PB	4 PB	8 PB	16 PB	24 PB	
2) 100% 4KB F 3) 100% 8KB	Rand. Write ²⁾	52 TB ²⁾	105TB	210TB	250 TB ²⁾	500 TB	1 PB	500 TB ²⁾	1 PB	2 PB	4 PB	1.8 PB ³⁾	3.5 PB	7 PB	10 PB	
	Seq. Write @ 64KB	207 GB	415 GB	830 GB	1 TB	2 TB	4 TB	2 TB	4 TB	8 TB	16 TB	4 TB	8 TB	16 TB	24 TB	
estimated allowed TBW per day for a life time of 3 years:	Ran. Write @ 4KB	52 GB	100 GB	210 GB	250 GB	500 GB	1 TB	500 GB	1 TB	2 TB	4 TB					
The state of the s	Ran. Write @ 8KB											1.8 TB	3.5 TB	7 TB	10 TB	
WPD random / Sequencial write (work load per day) ^D		0.6 / 2.5 @3 years			1 / 4 @ 5 years				2/8 @	a 5 years	•	5 / 12 @ 5 years				
Latency Random Read/write		0.28 ms/ 0.11 ms		0.13 ms/ 0.08 ms				0.13 ms	s/ 0.08 ms		-					
Controller		MDX (SATA 6.0G)		MDX (SATA 6.0G)				MDX (S	ATA 6.0G)		RDX (SAS Dual Port: 12.0G)					
NAND		21nm 64Gb TLC			21nm 64Gb MLC				21nm 6	4Gb MLC		21nm 64Gb Ep-MLC				
Form F	Form Factor		2.5" (7mm thickness)		2.5" (7mm thickness)			2.5" (7mn	m thickness)		2.5"(15mm thickness)					
Data -loss Protection		None			None				Yes, Ta	antal Cap		Yes, Super Capacitor				
	Over-Provisioning		7%			7%				7%		28%				
	Smart ID read out and setting Magician Tool Windows & Linux		Yes			Yes			١	/es		None				
Power Typ. (Active Wri		3.6W / 0.3W			3.4W / 0.3W				3.0W	/ 0.3W		9W / 4W (5V +12V)				
e)	Seq. Read / Write ^B @64k	520 / 330 MB/s 60KIOPS(TBD)			530 / 420 MB/s 70 KIOPS				500 / 4	100 MB/s		@ 128KB: Single Port : 497 / 435 MB/s Dual Port : 902 / 740 MB/s @ 4KB: Single Port : 72 KIOPS Dual Port : 101.5 KIOPS 8KB: Single Port: 50 KIOPS Dual Port: 81 KIOPS				
Performance	Ran. Read @4k								60 1	KIOPS						
Perf	Ran. Write ^c @4k	1.5/2.5/2.5 KIOPS			8.5 / 11.5 / 11.5 KIOPS				5.5 / 11 / 1	11 / 11 KIOPS		@4KB: Single / Dual Port : 30 KIOPS / 60KIOPS @8KB: 90 / 150 KIOPS				
its life cycle depends strongly on writir Tool for both windows and Linux platfo time in your environment, the extrapo	SSD vs. HDD: Smart ID & Life cycle The key advantage of SSD is its feature of having a forecastable life cycle. Lacking mechanical parts, its life cycle depends strongly on writing of data which can be tracked by electrical commands, the so-called SMART IDs. Our Magicin Tool for both windows and Linux platforms support you to track the amouth of data you write on SSD. If you track this over a period of time in your environment, the extrapolation will provide you with an exact figure of the life cycle of your SSD. the TBW figures should provide you an overview of expected life cycle.				Retention: Retention refers to the time that the cells in SSD keeping the data before a refresh needs to take place. virgin years retention based on the behavior of Flash cell built upor Flash cell are written, the higher the cell wears off and and to current increases.by the consumption of TBW the retention of months.			in SSD has up to 10 on. The more the I the leakage	a destructive proce The leakage current are connected to po	cle: SSD is based on N ss. The more the cell t increases, retention ower 24/7 as in the ca re of SSD could be adj can be adjusted.	is written the more t decreases. If the SSI ase of server implem	the cell is damged. On and so the cells entation could be 2) Perform a proof of concept				
Over-provisioning: The amount of the data intented to be written on SSD is not the same amount of data written on SSD. The background is mainly the basic characteristics of Flash. Writing is done page-wise, but deleting happens on a block. Any SSD needs free blocks to be able to write effectively. A designated physical area of the SSD which is not used for logical data allocations, called over-provisioning, helps the controller to allow for a broader write bandwidth. the higher the over-provisioning the better the write berfromance, withat trade-off of losing blocks for physical data. A TBW figures are preliminary, and will be updated by the end of the year 2012, subject of change, please ask you					soon as all cells are dramatically. Henc sure to have writte to get sustained re		e bandwidth decreas d evaluating SSD per his is called precond	ses partially formance, make	behavior of your ap figures and the calc	ement? SSD is not a d pplication is key to a ri ulated total GB per D ndwidth and perfrom	ight choice of SSD. Cl ay values to a get a f	TBW: Total Bytes Written is a key parameter for SSD. The data is provided above for the life cycle and a guidance of total GR part day Nothing is more critical to SSD than the				
	TBW figures are prelimianry, and will be sustained (after pre-conditioning) 100% 4				ur Samsung sales repre	sentative for the latest	information								Samsung	

TBW figures are prelimanny, and will be updated by the end of the year 2012, Subject of change, prease ask your satisfying sales representative on the lates sustained (after pre-conditioning) 100% 48B random write IOPS 24 hrs x 7 days x 365 days the higher the the write the write performance, the "up to" value refers to this aspect and reflects the performance of the highest density Number of time that SSD capacity could be writteb in Random Writes per day for the specified period time given till TBW is consumed

	Samsung			nominal speed and voltage		Syteme Behavior, Intel Xeon E5 max. population: DIMM/Channel									SAMSUNG			
Target Application	MEMORY Green DDR3 activated ECC REG (standard height)	Density	Rank	Speed	Voltage	1600@1.35V	1600@1.5V	1333@1.35V	1333@1.5V	1066@1.35V	1066@1.5V	800@13.35V	800@1.5V	Base Component	Technology Node	Power consumption at 100% loading*	Power consumption at idle *	Part Number
HPC, Cloud 2 & more socket servers, normal height of min. 1U, no	for max. 2TB in Westmere-EX 4 socket; needs 64 units, runs at 800; adpot Load reduced DIMM Modules fro Sandybridge 4 socket boards	32GB	4	1333	1,35	-	-	ı	-	-	П	-	Ш	4Gb	30nm	12W	4.0W	M393B4G70BM0-YH9
	Push product, highest flexibility , parity reached with 2x8GB	16GB	2	1600	1,35	I	П	П	П	П	Ξ	-	-	4Gb	30nm	6.4W	2.4W	M393B2G70BH0-YK0
foot-print and space limitations	Mainstream, highest volume and availability;	8GB	2	1600	1,35	I	П	П	П	П	Ξ	-	-	4Gb	30nm	2.6W	1.1W	M393B1G73BH0-YK0
illineations	Legacy product, to maximize bandwidth in small memory configurations, e.g. 12GB per Intel Xeon E5 2400 CPU	4GB	2	1600	1,35	I	П	П	П	П	Ш	-	-	2Gb	30nm	3.4W	1.0W	M393B5273DH0-YK0
	Load Reduced																	
BIG DATA, In-Memory , mainly	Only for Ivybridge platform	64GB	4	1333	1,35	-	-	1	П	Ш	Ш	-	-	4Gb	30nm	25W	11.6W	M386B8G70BO0-YH9
4 & more socket servers, mainly 3 DPC, high density	Small adder vs. normal REG DIMMs. It makes sense for usage of starting 2 DPC or higher population, due to higher bandwidth. Please note: slightly higher power consumption than RDIMM	32GB	4	1600	1,35	I	-	-	П	Ш	Ш	-	-	4Gb	30nm	13W	5.8W	M386B4G70BM0-YK0
while keeping up memory bandwidth	16GB RDIMM is a more preferred part.	16GB	4	1600	1,35	ı	-	-	П	Ш	Ш	-	-	4Gb	30nm	6.7W	3.4W	M386B2K70DM0-YK0
	ECC UNB / ECC UNB SO-DIMM																	
Dedicated server, Hosting 1 socket systems, 1600 speed is not needed.	ECC UNB SODIMM : Not a standard product. Project-based support, close alignment with Samsung sales required		2	1600	1,35	-	-	Ш	-	-	-	-	-	4Gb	30nm	2.7W	1.1W	M474B1G73BH0-YK0
			2	1600	1,35	-	-	П	-	-	-	-	-	2Gb	30nm	2.5W	1.0W	M474B5273DH0-YK0
	ECC UNB : Standard Product		2	1600	1,35	-	-	П	-	-	-	-	-	4Gb	30nm	2.7W	1.1W	M391B1G73BH0-YK0
			2	1600	1,35	-	-	Ш	-	-	-	-	-	2Gb	30nm	2.5W	1.0W	M391B5273DH0-YK0

Speed compatibility:

1600 speed is downward compatible with 1333, 1066 and 800. The speed is automatically identified by system BIOS and adjusted in the system based on the number of DIMMs per Channel (DPC). The speed adjustment is explained in the table above for each module category. Beyond the system adjustments, some platforms offer the option of speed enforcing with BIOS to a desired level (normally lower).

Voltage compatibility:

1,35V modules are upward compatible with 1,5V. i.e. a 1.35V Module will also work with a 1.5V setting. Many systems of INTEL EPSD, Supermicro etc allow the users to enforce and adjust the memory voltage on BIOS level. In this sense it is advisable to source 1.35V modules since they allow you to use them also at 1.5V. The voltage is automatically identified by the system BIOS and adjusted in the system based on the number of DIMMs per Channel (DPC).

Sourcing recommendation:

In order to reduce the amount of part numbers, consequently reducing the inventory level and increasing the flexibility, Samsung recommends to generally use the 1600 1.35V parts. These parts come with no adder or premium to other voltage and speed options, and they are downwards compatible through BIOS setting to the desired speed and voltage seeting of your application. (coampare with the table on the right)

Process Technology:

The lower the number the more features come with the parts. 1600 speed in combination with 1,35V is the main output of 30nm technology. That is why Samsung does not ask for a premium. And we recommend to focus on one part number per product density to reduce the inventory, easier planning and importing to different plaforms and applications.

you can recognize sss technology on the modues you use with hints on the Module sticker.

G2 = 30nm; stands for Generation 2 of Samsung Green Products

1600/1.35V RDIMM fits all

1600/1.3	SSV RDIMINI t	its all					
DIMM spee	ed and Volatge		System spec	ed and volta	ge		
DPC config.	or pre installed DIMM	added DIMM as upgrade	1600/1.35V	1600/1.5V	1333/1.35V	1333/1.5V	1066/1.5V
1 DPC	1600/1.35V	N.A.	(x)	(x)	x		
2DPC	1600/1.35V	1600/1.35V	(x)	(x)	×		
2DPC	1600/1.5V	1600/1.35V		(x)		×	
2DPC	1333/1.35V	1600/1.35V			x	(x)	
2DPC	1333/1.5V	1600/1.35V				x	
2DPC	1066/1.35V	1600/1.35V					х

Sandybridge 2 socket system

X = the setting adjusted in system automatically without BIOS setting changes

(x) = BIOS Option, BIOS setup of manufacturer; available on INTEL EPSD and supermicro boards BIOS